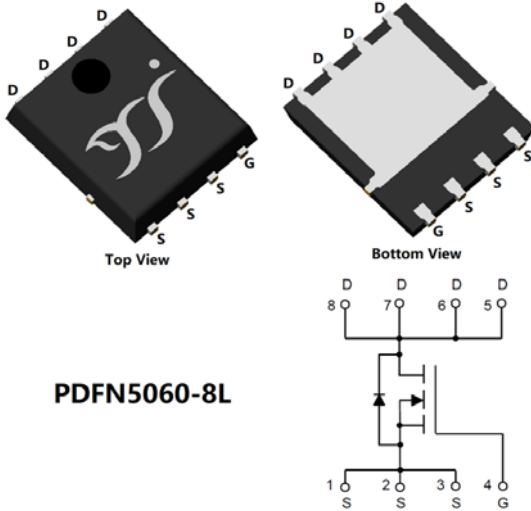


N-Channel Enhancement Mode Field Effect Transistor



PDFN5060-8L

Product Summary

- V_{DS} 60V
- I_D 95A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) $< 3.8\text{mohm}$
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) $< 4.5\text{mohm}$
- 100% EAS Tested
- 100% ∇V_{DS} Tested

General Description

- Split gate trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Part no. with suffix "Q" means AEC-Q101 qualified

Applications

- High Frequency Switching
- Synchronous Rectification
- 12V and 24V Automotive systems

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	60	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current	$T_C=25^\circ\text{C}$	I_D	95	A
	$T_C=100^\circ\text{C}$		60	
Pulsed Drain Current ^A		I_{DM}	390	A
Avalanche energy ^B		EAS	1200	mJ
Total Power Dissipation ^C	$T_C=25^\circ\text{C}$	P_D	113	W
	$T_C=100^\circ\text{C}$		45	
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	$^\circ\text{C}$

■ Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient ^D	Steady-State	$R_{\theta JA}$	38	50	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	0.9	1.1	

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJG95G06AQ	F1	YJG95G06A	5000	10000	100000	13" reel



YJG95G06AQ

■ Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	1.2	1.7	2.5	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =20A		2.9	3.8	mΩ
		V _{GS} =4.5V, I _D =15A		3.2	4.5	mΩ
Diode Forward Voltage	V _{SD}	I _S =20A, V _{GS} =0V			1.2	V
Gate resistance	R _G	f=1MHz		2		Ω
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f=1MHZ		5300		pF
Output Capacitance	C _{oss}			1500		
Reverse Transfer Capacitance	C _{rss}			70		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =10V, V _{DS} =30V, I _D =45A		85		nC
Gate-Source Charge	Q _{gs}			23		
Gate-Drain Charge	Q _{gd}			9.3		
Reverse Recovery Charge	Q _{rr}	I _S =45A, di/dt=100A/us,		61		
Reverse Recovery Time	t _{rr}			54		
Turn-on Delay Time	t _{D(on)}	V _{GS} =10V, V _{DS} =30V, I _D =45A R _{GEN} =3Ω		18.5		ns
Turn-on Rise Time	t _r			87		
Turn-off Delay Time	t _{D(off)}			64		
Turn-off fall Time	t _f			107		

A. Repetitive rating; pulse width limited by max. junction temperature.

B. V_{DD}=50V, R_G=25Ω, L=6mH, I_{AS}=20A

C. P_d is based on max. junction temperature, using junction-case thermal resistance.

D. The value of R_{θJA} is measured with the device mounted on the minimum recommend pad size, in the still air environment with T_A =25°C.

The maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.



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■ Typical Performance Characteristics

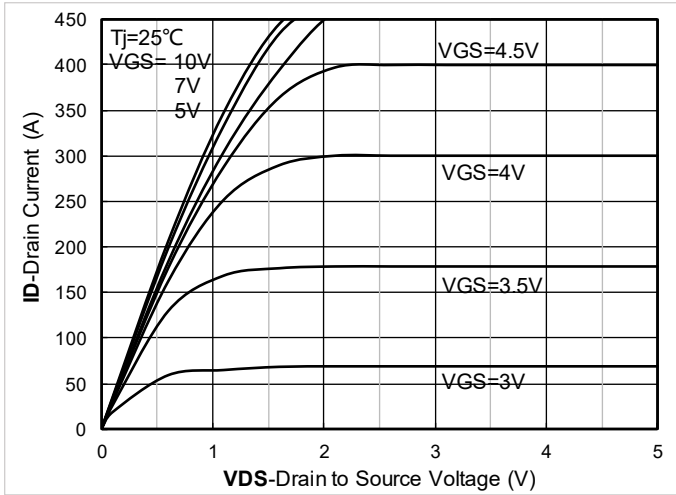


Figure 1. Output Characteristics

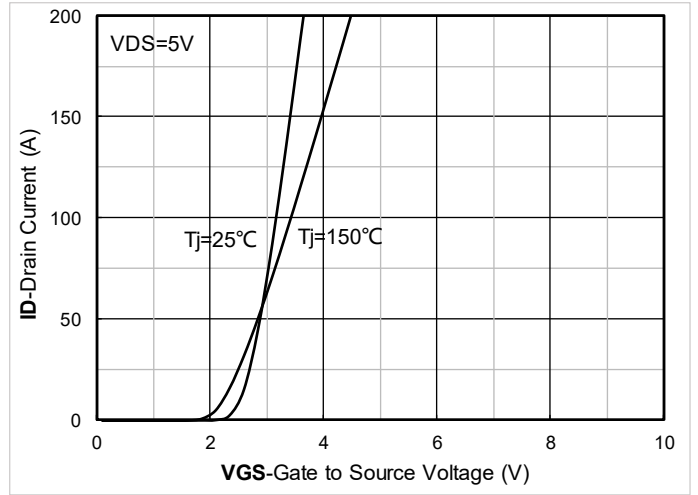


Figure 2. Transfer Characteristics

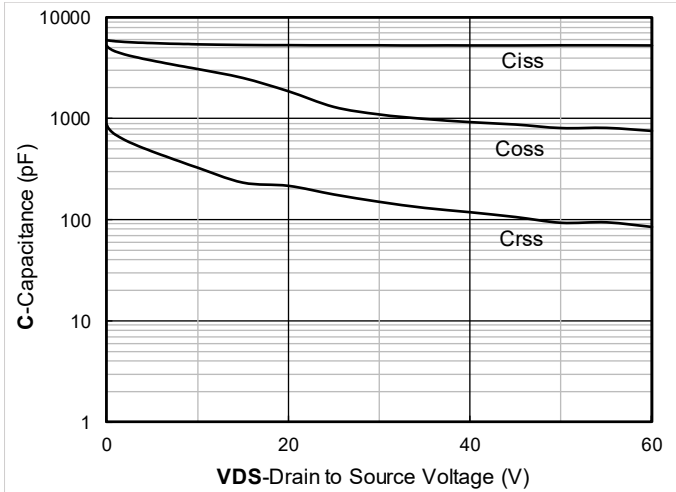


Figure 3. Capacitance Characteristics

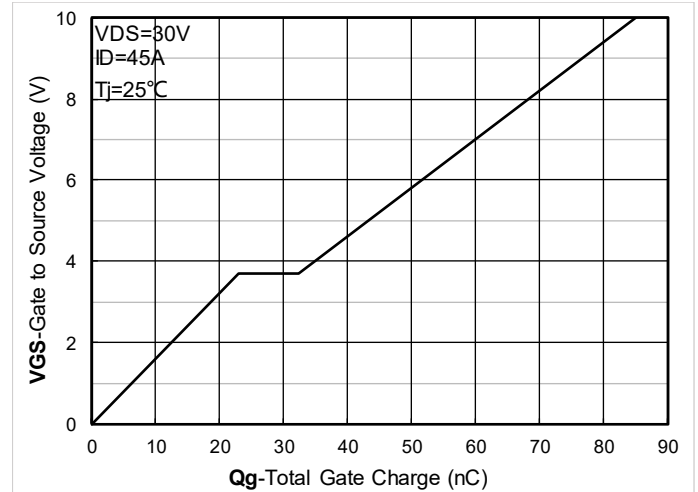


Figure 4. Gate Charge

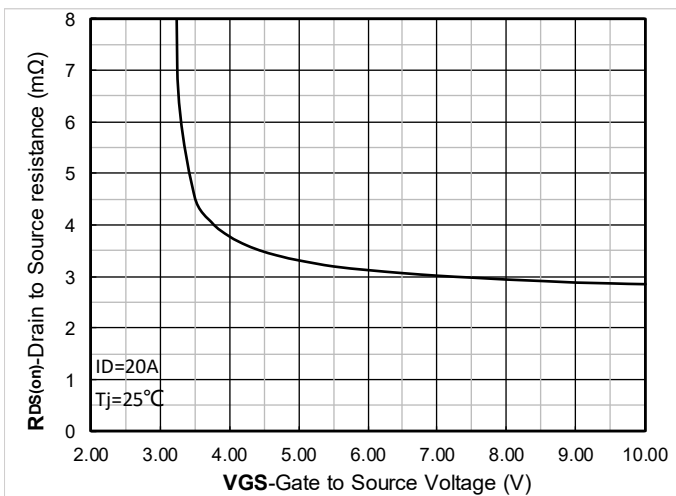


Figure 5. On-Resistance vs Gate to Source Voltage

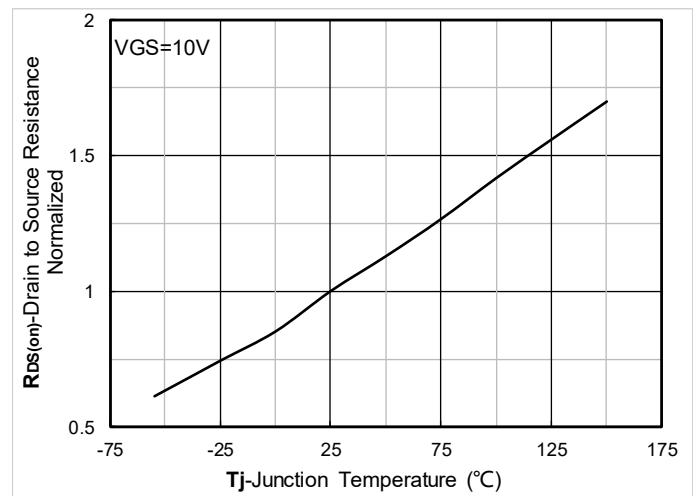


Figure 6. Normalized On-Resistance



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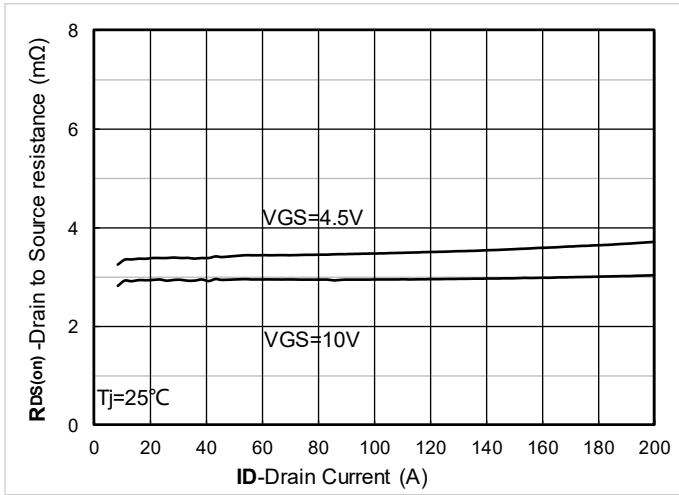


Figure 7. RDS(on) VS Drain Current

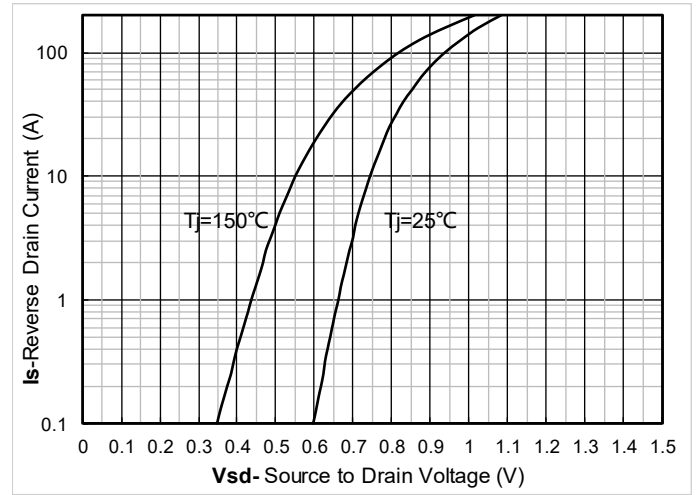


Figure 8. Forward characteristics of reverse diode

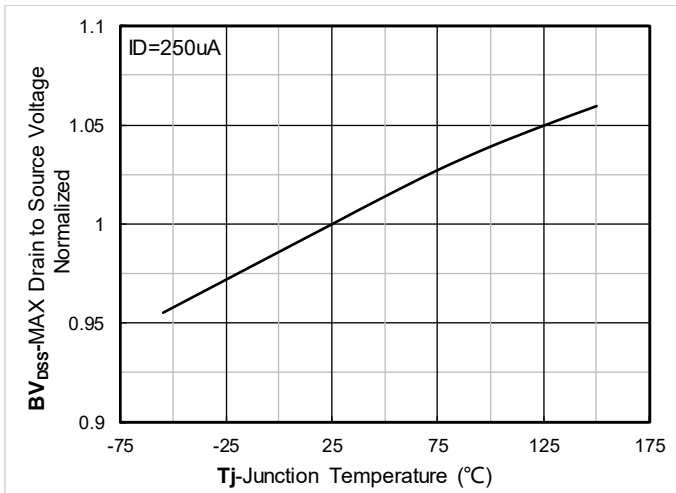


Figure 9. Normalized breakdown voltage

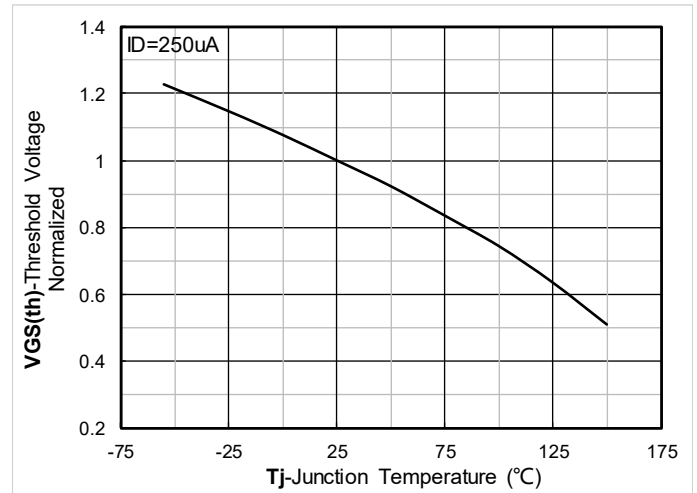


Figure 10. Normalized Threshold voltage

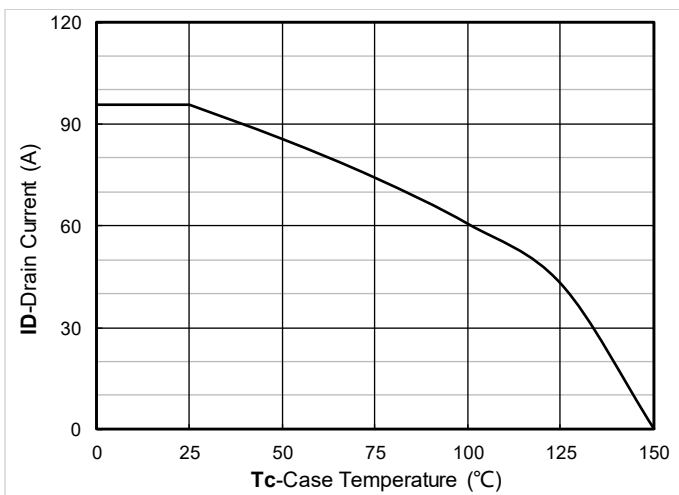


Figure 11. Current dissipation

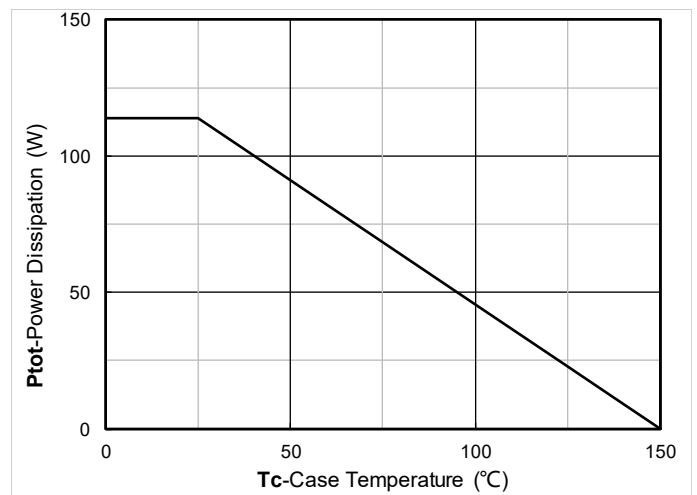


Figure 12. Power dissipation



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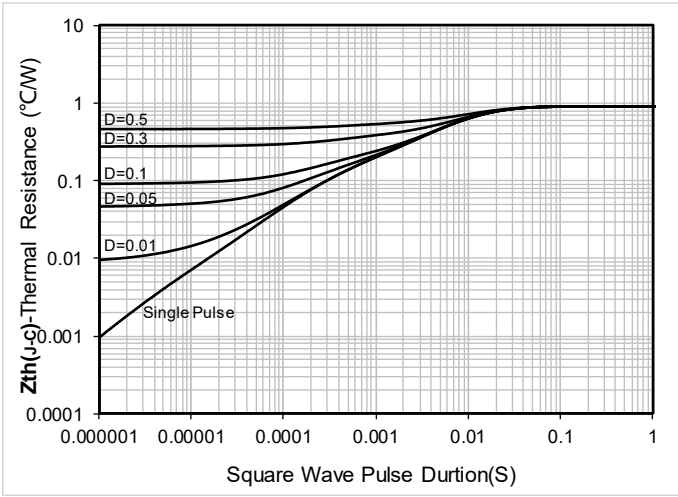


Figure 13. Maximum Transient Thermal Impedance

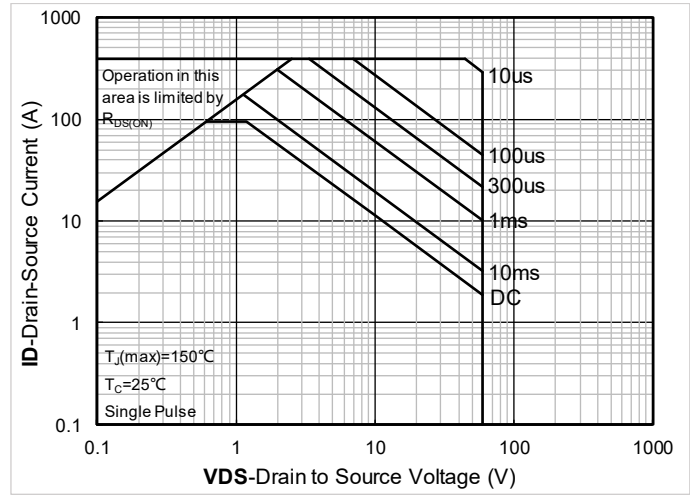
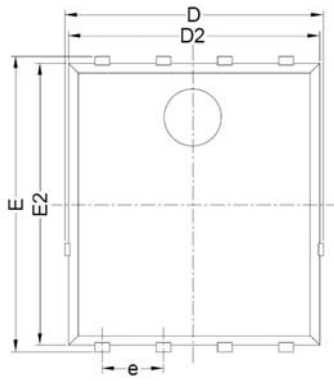


Figure 14. Safe Operation Area

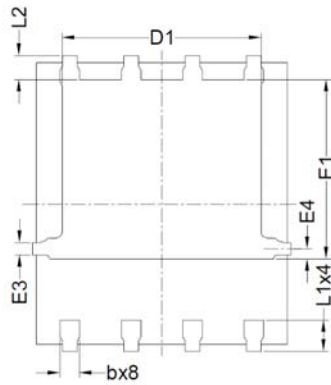


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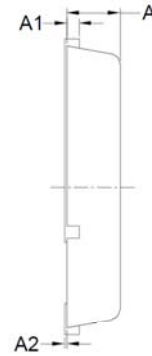
■ PDFN5060 Package information



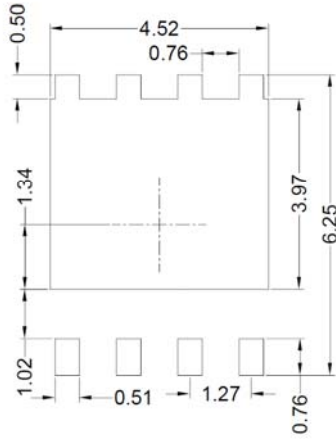
Top View
正面视图



Bottom View
背面视图



Side View
侧面视图



Suggested Solder Pad Layout
Top View

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.15	6.35
A	1.00	1.10	1.20
A1	0.254 BSC		
A2			0.10
D1	3.92	4.12	4.32
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
E3	0.254 REF		
E4	0.21 REF		
L1	0.56	0.66	0.76
L2	0.50 BSC		
b	0.31	0.41	0.51
e	1.27 BSC		

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.10 mm.
3. The pad layout is for reference purposes only.



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